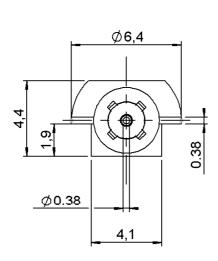
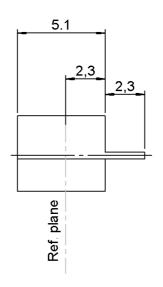
SMT TYPE - EDGE CARD - LIMITED DETENT

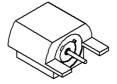
R222.423.320

Series : **SMP**





Scale: 1/1



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL BERYLLIUM COPPER - PTFE	GOLD 1.3 OVER NICKEL2 GOLD 1.27 OVER NICKEL 1.27

Issue: 1449 E

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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SMT TYPE - EDGE CARD - LIMITED DETENT

Series: SMP

PACKAGING

Standard	Unit W' ention	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

50 Ω **0-18** GHz Impedance Frequency

VSWR **1.50** + **0.0000** x F(GHz) Maxi Insertion loss **0.12** $\sqrt{F(GHz)}$ dB Maxi - F(GHz)) dB Maxi

RF leakage 335 Veff Maxi Voltage rating Dielectric withstanding voltage 500 Veff mini 5000 $M\Omega$ mini Insulation resistance

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal Atm.cm3/s Panel leakage

OTHER CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end **6.8** N mini Axial force – Opposite end **6.8** N mini Torque NA N.cm mini

Recommended torque

N.cm Mating Panel nut N.cm

500 Cycles mini Mating life

Weight **0.6600** g

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Series: SMP

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

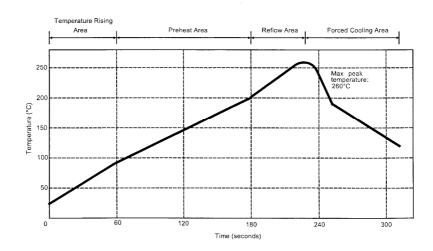
We advise a thickness of 150 microns (.5.9 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

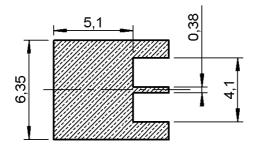
Issue: 1449 E In the effort to improve our products, we reserve the right to make changes judged to be necessary.



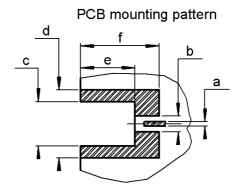
R222.423.320

SMT TYPE - EDGE CARD - LIMITED DETENT

Series : SMP



Shadow of receptacle for video camera



а	0,48	
b	1,5	
С	4,18 - 4,32	
d	6,5	
е	4,95 - 5,45	
f	7,52	

Issue: 1449 E

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